

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:
a substrate;
a pixel portion over the substrate;
a driving circuit over the substrate and having at least one first terminal; and
a layer comprising an integrated circuit having at least one second terminal, the integrated circuit at least partially overlapped with the driving circuit,
wherein the first terminal and the second terminal face each other, and are electrically connected via a conductive material, and
wherein the layer does not overlap the pixel portion.
2. (Original) The semiconductor device according to claim 1,
wherein the integrated circuit includes any one of a display controller, a frame memory, a power source circuit, a CPU and a memory.
3. (Original) The semiconductor device according to claim 1,
wherein the pixel portion includes any one of a light-emitting element and a liquid crystal element.
4. (Previously Presented) The semiconductor device according to claim 1,
wherein the pixel portion includes a light-emitting element having a first electrode, an electroluminescent layer and a second electrode, and
wherein the first electrode and the second electrode are translucent.

5. (Original) The semiconductor device according to claim 1,
wherein the semiconductor device is any one of an active matrix type semiconductor device and a passive matrix type semiconductor device.

6. (Previously Presented) An electronic device comprising the semiconductor device according to claim 1,

wherein the electronic device is any one of a group comprising a display device, a notebook type personal computer, a mobile computer, a player with a recording medium, an electronic book, a video camera, a portable telephone, a digital camera, a head-mount display, a car navigation system, a projector and a car stereo.

7. (Previously Presented) The semiconductor device according to claim 1,
wherein the integrated circuit is formed by transcribing an element formation layer formed over a second substrate.

8. (Canceled)

9. (Original) The semiconductor device according to claim 7,
wherein the integrated circuit is formed by laminating the integrated circuit in one layer or two or more layers.

10-13. (Canceled)

14. (Previously Presented) The semiconductor device according to claim 1,
wherein the integrated circuit is electrically connected to part or an entirety of the pixel portion and the driving circuit.

15-26. (Canceled)

27. (Currently Amended) A semiconductor device comprising:

a substrate;
a pixel portion over the substrate;
a driving circuit over the substrate; and
an integrated circuit at least partially overlapped with the driving circuit, with an adhesive layer therebetween,

wherein the integrated circuit comprises a first transistor at least partially overlapped with the adhesive layer and a second transistor at least partially overlapped with the adhesive layer.

28. (Previously Presented) The semiconductor device according to claim 27,
wherein the integrated circuit includes any one of a display controller, a frame memory, a power source circuit, a CPU and a memory.

29. (Previously Presented) The semiconductor device according to claim 27,
wherein the pixel portion includes any one of a light-emitting element and a liquid crystal element.

30. (Previously Presented) The semiconductor device according to claim 27,
wherein the pixel portion includes a light-emitting element having a first electrode, an electroluminescent layer and a second electrode, and
wherein the first electrode and the second electrode are translucent.

31. (Previously Presented) The semiconductor device according to claim 27,
wherein the semiconductor device is any one of an active matrix type semiconductor device and a passive matrix type semiconductor device.

32. (Previously Presented) An electronic device comprising the semiconductor device according to claim 27,
wherein the electronic device is any one of a group comprising a display device, a notebook type personal computer, a mobile computer, a player with a recording medium, an

electronic book, a video camera, a portable telephone, a digital camera, a head-mount display, a car navigation system, a projector and a car stereo.

33. (Previously Presented) The semiconductor device according to claim 27, wherein the integrated circuit is formed by transcribing an element formation layer formed over a second substrate.

34. (Previously Presented) The semiconductor device according to claim 33, wherein the integrated circuit is formed by laminating the integrated circuit in one layer or two or more layers.

35. (Previously Presented) The semiconductor device according to claim 27, wherein the integrated circuit is electrically connected to part or an entirety of the pixel portion and the driving circuit.

36. (Currently Amended) A semiconductor device comprising:
a substrate;
a first layer comprising:
a pixel portion over the substrate,[[;]] and
a driving circuit over the substrate; [[and]]
a second layer comprising a first integrated circuit at least partially overlapped with the driving circuit; and
a third layer comprising a second integrated circuit at least partially overlapped with the first integrated circuit.

37. (Previously Presented) The semiconductor device according to claim 36, wherein the integrated circuit includes any one of a display controller, a frame memory, a power source circuit, a CPU and a memory.

38. (Previously Presented) The semiconductor device according to claim 36,

wherein the pixel portion includes any one of a light-emitting element and a liquid crystal element.

39. (Previously Presented) The semiconductor device according to claim 36,
wherein the pixel portion includes a light-emitting element having a first electrode, an electroluminescent layer and a second electrode, and
wherein the first electrode and the second electrode are translucent.

40. (Previously Presented) The semiconductor device according to claim 36,
wherein the semiconductor device is any one of an active matrix type semiconductor device and a passive matrix type semiconductor device.

41. (Previously Presented) An electronic device comprising the semiconductor device according to claim 36,
wherein the electronic device is any one of a group comprising a display device, a notebook type personal computer, a mobile computer, a player with a recording medium, an electronic book, a video camera, a portable telephone, a digital camera, a head-mount display, a car navigation system, a projector and a car stereo.

42. (Previously Presented) The semiconductor device according to claim 36,
wherein the integrated circuit is formed by transcribing an element formation layer formed over a second substrate.

43. (Previously Presented) The semiconductor device according to claim 42,
wherein the integrated circuit is formed by laminating the integrated circuit in one layer or two or more layers.

44. (Previously Presented) The semiconductor device according to claim 36,
wherein the integrated circuit is electrically connected to part or an entirety of the pixel portion and the driving circuit.

45. (Currently Amended) A semiconductor device comprising:
a substrate;
a pixel portion over the substrate;
a driving circuit over the substrate, having at least one first terminal; and
an integrated circuit having at least one second terminal and at least partially overlapped with the driving circuit, with an adhesive layer therebetween,
wherein the first terminal and the second terminal face each other, and are electrically connected via a conductive material, and
wherein the integrated circuit comprises a first transistor at least partially overlapped with the adhesive layer and a second transistor at least partially overlapped with the adhesive layer.

46. (Previously Presented) The semiconductor device according to claim 45,
wherein the integrated circuit includes any one of a display controller, a frame memory, a power source circuit, a CPU and a memory.

47. (Previously Presented) The semiconductor device according to claim 45,
wherein the pixel portion includes any one of a light-emitting element and a liquid crystal element.

48. (Previously Presented) The semiconductor device according to claim 45,
wherein the pixel portion includes a light-emitting element having a first electrode, an electroluminescent layer and a second electrode, and
wherein the first electrode and the second electrode are translucent.

49. (Previously Presented) The semiconductor device according to claim 45,
wherein the semiconductor device is any one of an active matrix type semiconductor device and a passive matrix type semiconductor device.

50. (Previously Presented) An electronic device comprising the semiconductor device according to claim 45,

wherein the electronic device is any one of a group comprising a display device, a notebook type personal computer, a mobile computer, a player with a recording medium, an electronic book, a video camera, a portable telephone, a digital camera, a head-mount display, a car navigation system, a projector and a car stereo.

51. (Previously Presented) The semiconductor device according to claim 45,
wherein the integrated circuit is formed by transcribing an element formation layer formed over a second substrate.

52. (Previously Presented) The semiconductor device according to claim 51,
wherein the integrated circuit is formed by laminating the integrated circuit in one layer or two or more layers.

53. (Previously Presented) The semiconductor device according to claim 45,
wherein the integrated circuit is electrically connected to part or an entirety of the pixel portion and the driving circuit.

54. (Currently Amended) A semiconductor device comprising:
a substrate;
a first layer comprising:
a pixel portion over the substrate,[[;]] and
a driving circuit over the substrate; [[and]]
a second layer comprising a first integrated circuit at least partially overlapped with the driving circuit, with a first adhesive layer therebetween; and
a third layer comprising a second integrated circuit at least partially overlapped with the first integrated circuit, with a second adhesive layer therebetween.

55. (Previously Presented) The semiconductor device according to claim 54,

wherein the integrated circuit includes any one of a display controller, a frame memory, a power source circuit, a CPU and a memory.

56. (Previously Presented) The semiconductor device according to claim 54, wherein the pixel portion includes any one of a light-emitting element and a liquid crystal element.

57. (Previously Presented) The semiconductor device according to claim 54, wherein the pixel portion includes a light-emitting element having a first electrode, an electroluminescent layer and a second electrode, and wherein the first electrode and the second electrode are translucent.

58. (Previously Presented) The semiconductor device according to claim 54, wherein the semiconductor device is any one of an active matrix type semiconductor device and a passive matrix type semiconductor device.

59. (Previously Presented) An electronic device comprising the semiconductor device according to claim 54, wherein the electronic device is any one of a group comprising a display device, a notebook type personal computer, a mobile computer, a player with a recording medium, an electronic book, a video camera, a portable telephone, a digital camera, a head-mount display, a car navigation system, a projector and a car stereo.

60. (Previously Presented) The semiconductor device according to claim 54, wherein the integrated circuit is formed by transcribing an element formation layer formed over a second substrate.

61. (Previously Presented) The semiconductor device according to claim 60, wherein the integrated circuit is formed by laminating the integrated circuit in one layer or two or more layers.

62. (Previously Presented) The semiconductor device according to claim 54, wherein the integrated circuit is electrically connected to part or an entirety of the pixel portion and the driving circuit.

63. (Currently Amended) A semiconductor device comprising:
a substrate;
a first layer comprising:
a pixel portion over the substrate; and
a driving circuit over the substrate, having at least one first terminal;
a second layer comprising a first integrated circuit having at least one second terminal and at least one third terminal, and at least partially overlapped with the driving circuit, with a first adhesive layer therebetween; and
a third layer comprising a second integrated circuit having at least one fourth terminal and at least partially overlapped with the first integrated circuit, with a second adhesive layer therebetween,
wherein the first terminal and the second terminal face each other, and are electrically connected via a first conductive material, and
wherein the third terminal and the fourth terminal face each other, and are electrically connected via a second conductive material.

64. (Previously Presented) The semiconductor device according to claim 63, wherein the integrated circuit includes any one of a display controller, a frame memory, a power source circuit, a CPU and a memory.

65. (Previously Presented) The semiconductor device according to claim 63, wherein the pixel portion includes any one of a light-emitting element and a liquid crystal element.

66. (Previously Presented) The semiconductor device according to claim 63,

wherein the pixel portion includes a light-emitting element having a first electrode, an electroluminescent layer and a second electrode, and

wherein the first electrode and the second electrode are translucent.

67. (Previously Presented) The semiconductor device according to claim 63,
wherein the semiconductor device is any one of an active matrix type semiconductor device and a passive matrix type semiconductor device.

68. (Previously Presented) An electronic device comprising the semiconductor device according to claim 63,

wherein the electronic device is any one of a group comprising a display device, a notebook type personal computer, a mobile computer, a player with a recording medium, an electronic book, a video camera, a portable telephone, a digital camera, a head-mount display, a car navigation system, a projector and a car stereo.

69. (Previously Presented) The semiconductor device according to claim 63,
wherein the integrated circuit is formed by transcribing an element formation layer formed over a second substrate.

70. (Previously Presented) The semiconductor device according to claim 69,
wherein the integrated circuit is formed by laminating the integrated circuit in one layer or two or more layers.

71. (Previously Presented) The semiconductor device according to claim 63,
wherein the integrated circuit is electrically connected to part or an entirety of the pixel portion and the driving circuit.